

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Serial Number: 09/733,289

Filing Date: December 8, 2000

Title: Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers

Page 2

Dkt: 884.798US1

Please delete claim 5.

Please add the following new claim.

29. (New) The microelectronic package of claim 1, further including:

a microelectronic package core having a first surface and an opposing second surface, said microelectronic package core having at least one opening defined therein extending from said microelectronic package core first surface to said microelectronic package core second surface, where said microelectronic package core second surface abuts said heat sink; and

wherein the at least one microelectronic die is disposed within said at least one microelectronic package core opening and adjacent said heat sink, said at least one microelectronic die having an active surface, and a patterned thermally conductive adhesive layer disposed between said at least one microelectronic die and said heat sink.

REMARKS

Applicant has carefully reviewed and considered the Office Action mailed on July 1, 2002, and the references cited therewith.

Claim 1 is amended, claim 5 is canceled, and claim 29 is added; as a result, claims 1-4, 10-17, and 29 are now pending in this application. No new matter was added by this amendment. Support for the amendment of claim 1 comes from cancelled claim 5 and the specification at page 6, beginning at line 16 and throughout the disclosure. Support for new claim 29 comes from claim 1, claim 10, and throughout the disclosure.

Rejections Under 35 U.S.C. §102

Claim 1 was rejected under 35 U.S.C. §102(e) as being anticipated by Chen et al. (U.S. Patent No. 6,160,311). Claim 1 has been amended, including adding the limitation of cancelled claim 5. By the amendment of claim 1, the rejection is mooted. Chen neither teaches nor suggests the limitations of claim 1 as amended. Withdrawal of the rejection is respectfully requested.